

LMN2122JZF-20V N-Channel Enhancement Mode MOSFET

Features

- 20V/6.3A, $R_{DS(ON)}=22m\Omega@V_{GS}=4.5V$
- Super high design cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design

provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

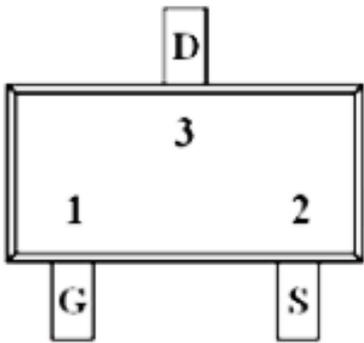
Product Description

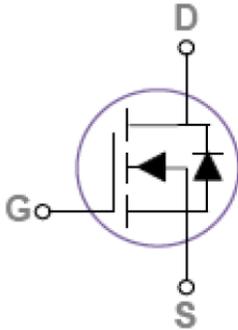
LMN2122JZF, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to

Applications

- Portable Equipment
- Battery Powered System
- Net Working System

Pin Configuration

LMN2122JZF (SOT-23)	
	
PIN	Description
1	Gate
2	Source
3	Drain



Ordering Information

<u>LMN2122</u>	<u>JZ</u>	<u>E</u>
LFC P/N	PKG code	Pb Free code

Marking Information

Part Number	Package	Part Marking	Quantity
LMN2122JZF	SOT-23	22XWM	3000pcs

Absolute Maximum Ratings

 (T_C=25°C Unless otherwise noted)

Symbol	Parameter	Typical	Unit	
V _{DS}	Drain-Source Voltage	20	V	
V _{GS}	Gate-Source Voltage	± 12	V	
I _D	Continuous Drain Current	TC=25°C	6.3	A
		TC=70°C	5	
I _{DM}	Pulsed Drain Current ¹	24	A	
P _D	Power Dissipation	TC=25°C	1.25	W
		TC=70°C	0.8	W/°C
T _J	Operating Junction Temperature	-50/150	°C	
T _{STG}	Storage Temperature Range	-50/150	°C	
R _{θJA}	Thermal Resistance-Junction to Ambient	100	°C/W	

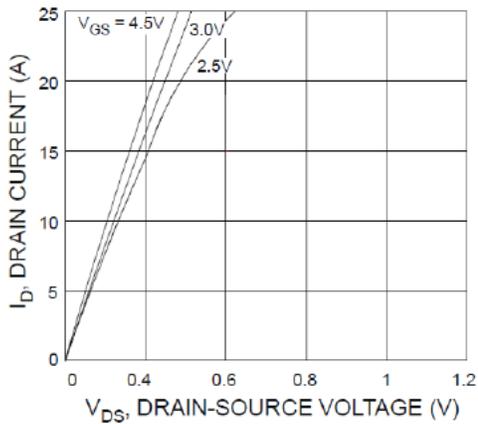
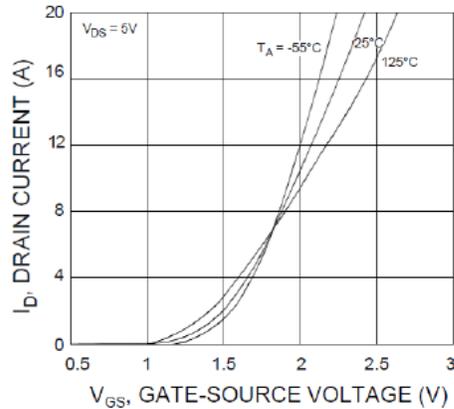
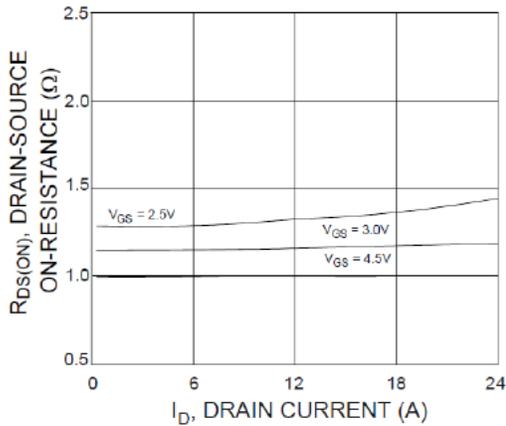
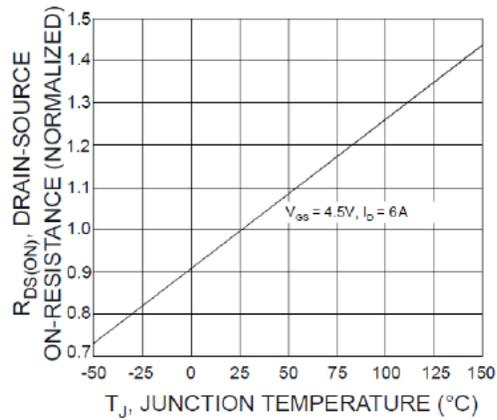
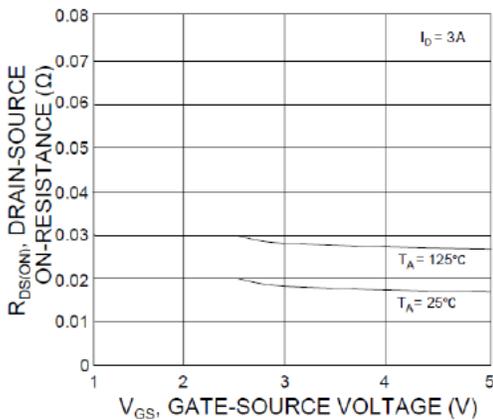
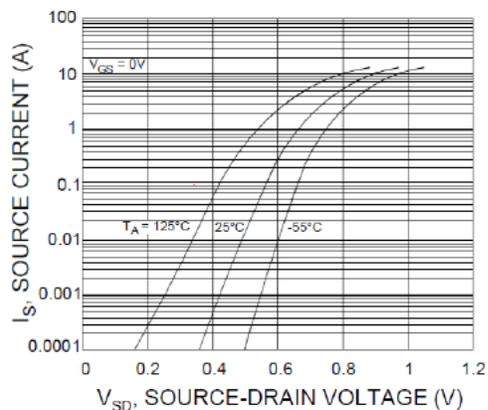
Electrical Characteristics

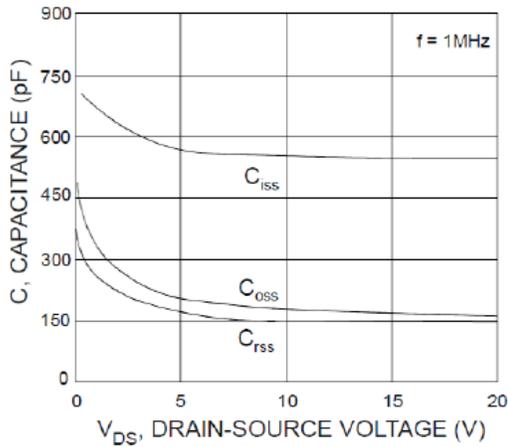
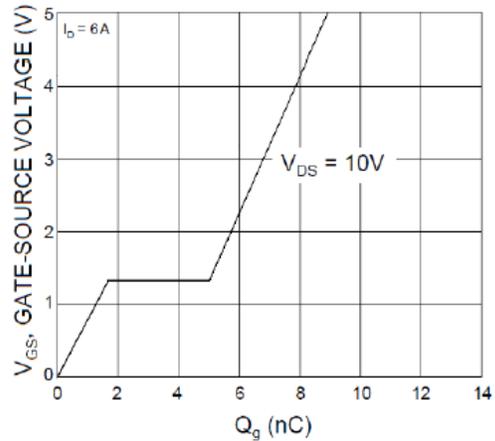
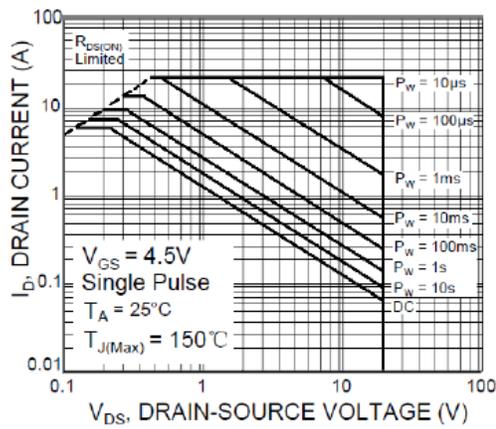
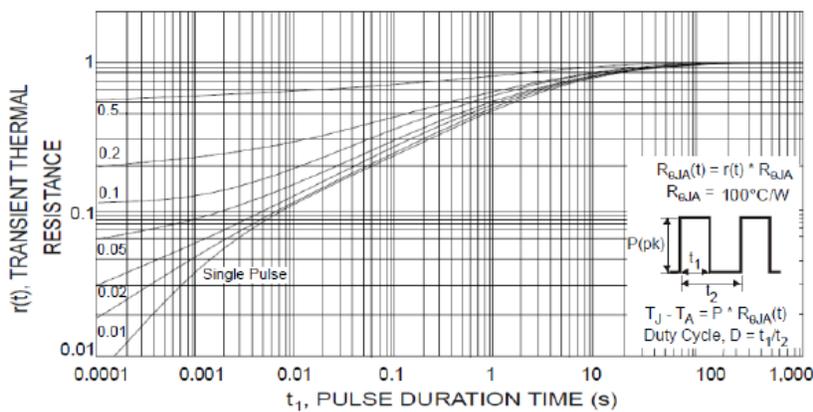
 (T_C=25°C Unless otherwise noted)

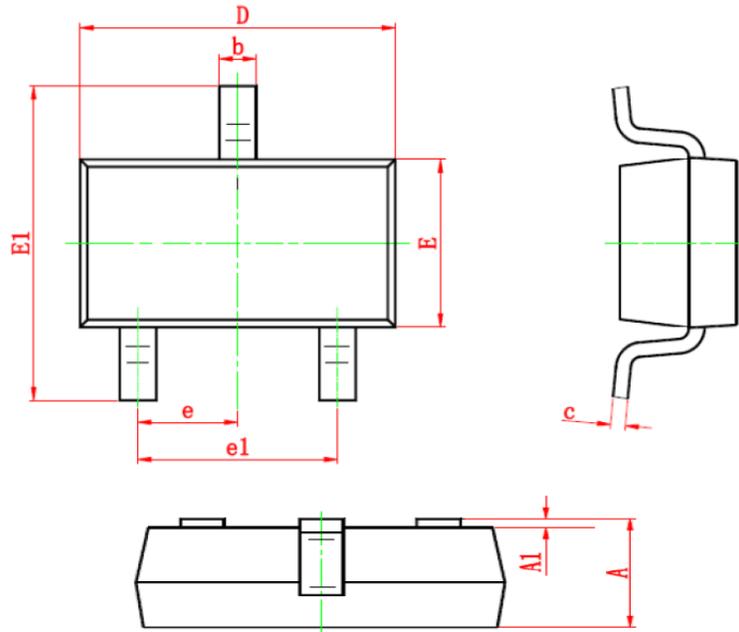
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Static							
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	20			V	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	0.4		1	V	
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±12V			± 100	nA	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V			1	uA	
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =4.5V, I _D =4A		16	22	mΩ	
		V _{GS} =2.5V, I _D =3A		22	29		
		V _{DS} =1.8V, I _D =2A		33	45		
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =3A		3.7		S	
Dynamic							
Q _g	Total Gate Charge ^{1,2}	V _{DS} =10V, V _{GS} =4.5V, I _D =6A		8.5		nC	
Q _{gs}	Gate-Source Charge ^{1,2}			1.5			
Q _{gd}	Gate-Drain Charge ^{1,2}			3.5			
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1MHz		560		pF	
C _{oss}	Output Capacitance			166			
C _{rss}	Reverse Transfer Capacitance			150			
t _{d(on)}	Turn-On Time ^{2,3}	V _{DD} =10V, I _D =1A, V _{GS} =4.5V, R _G =6Ω		12		ns	
t _r				15			
t _{d(off)}			Turn-Off Time ^{2,3}		30		
t _f					15		
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V			1	V	

Note:

1. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
2. Independent of operating temperature.

Typical Performance Characteristics

Fig.1 Typical Output Characteristics

Fig.2 Typical Transfer Characteristic

Figure.3 Typical On-Resistance vs. Drain Current and Gate Voltage

Figure.4 On-Resistance Variation with T_j

Fig.5 On-Resistance Variation with Drain Current and Gate Voltage

Fig.6 Diode Forward Voltage vs. Current


Fig.7 Capacitance Characteristics

Fig.8 Gate Charge Characteristics

Fig.9 Maximum Safe Operation Area

Fig.10 Normalized Transient Impedance

Package

Dimension:

Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.140	0.035	0.045
A1	0.000	0.140	0.000	0.006
b	0.300	0.510	0.012	0.020
c	0.070	0.180	0.003	0.007
D	2.800	3.040	0.110	0.120
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.780	2.050	0.070	0.081

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